



15th

# EMC Compo 2026

*International Workshop on the Electromagnetic Compatibility of Integrated Circuits*



**EMC COMPO 2026**

December 7<sup>th</sup> - 10<sup>th</sup>, 2026

Okayama Convention Center  
Okayama City, Japan



## ***Important Date***

Deadline for paper submission **May 31, 2026**

Notification of acceptance **Aug. 17, 2026**

Final paper submission **Sep. 25, 2026**

## ***Organization and venue***

Welcome to Japan — the land where tradition meets cutting-edge technology! Following the successful edition held at Torino in 2024, the EMC community will gather again at the Okayama Convention Center, Japan, from Dec. 7th to 10th, 2026, to share the latest advances and exchange ideas on research progress and technological developments in the various topics described below. The 15th International Workshop on Electromagnetic Compatibility of Integrated Circuits (EMC COMPO 2026) is organized by the Institute of Electronics, Information and Communication Engineers (IEICE) and technically co-sponsored by the IEEE EMC Society.

## ***Information for authors***

Authors are invited to submit original contributions in two column and either one-page format for abstract submission (in proceedings only) or full-length format for paper submission (for IEEE Xplore Publication) through the online submission system. For full-length papers, the suggested length is between 2 and 4 pages. The paper must follow the IEEE two-column A4 format for Conference Proceedings.

## Topics

Topics of interest include, but are not limited to, the following:

- EMC of core blocks and I/Os
- Substrate coupling in smart power ICs
- Materials for improved EMC of ICs
- Modeling for IC-level EMC
- EMC-aware design of ICs and design guidelines
- Tools to handle EMC at IC and module level
- SI and PI at IC and PCB level
- EMC issues in SoC, SiP, chiplet, and 3D ICs
- Package, interposer, and PDN effects on IC EMC
- Susceptibility to EMI of analog and mixed-signal IPs
- Automotive IC EMC
- EMC of analog and digital sensors
- EMC of ICs for wireline communications
- Power electronics EMC/EMI
- EMC of ICs for biomedical applications
- EMC Challenges of AI and Machine Learning ICs
- EM Security and Electromagnetic Reliability of ICs
- Measurement methods for chip-level EMC
- EMC standards and regulations
- Long-term electromagnetic robustness of ICs
- Influence of IC EMC on system design

## Awards

The Best Paper Award will recognize outstanding academic research in IC EMC. The Best Student Award will be given to a full-length paper whose first and presenting author is a student.

## Sponsorship

It is also possible to take advantage of many sponsorship opportunities. Proposals of Diamond Sponsor, Gold Sponsor and Silver Sponsor packages are available, but any form of sponsoring (technical, financial or any other) to promote the workshop is very welcome. To become a conference sponsor please write to [contact@emccompo2026.jp](mailto:contact@emccompo2026.jp).

## Tutorials and short courses

Tutorials and short courses will be organized as interactive educational presentations to provide up-to-date practical help to those who are new to the subject or who require an update, as well as to address in-depth topical subjects. For accepted proposals, the tutorial organizer will be responsible for soliciting presentations, corresponding with session speakers, communicating with the Workshop Local Committee, and moderating the session at the workshop. Please send tutorial and short course proposals to [contact@emccompo2026.jp](mailto:contact@emccompo2026.jp) by July 31st, 2026.

## Contact information

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## Organizing committee

### General Chair

Makoto Nagata, Kobe University

### TPC Chair

Tohlu Matsushima, Kyushu Institute of Technology

### Members

Yoshitaka Toyota, Okayama University  
Yuichi Hayashi, NAIST  
Kengo Iokibe, Okayama University  
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